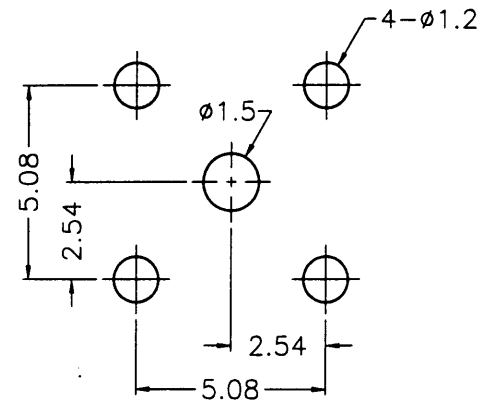
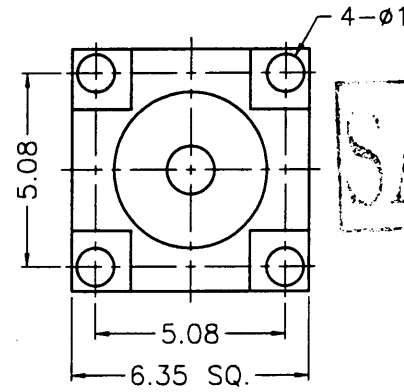
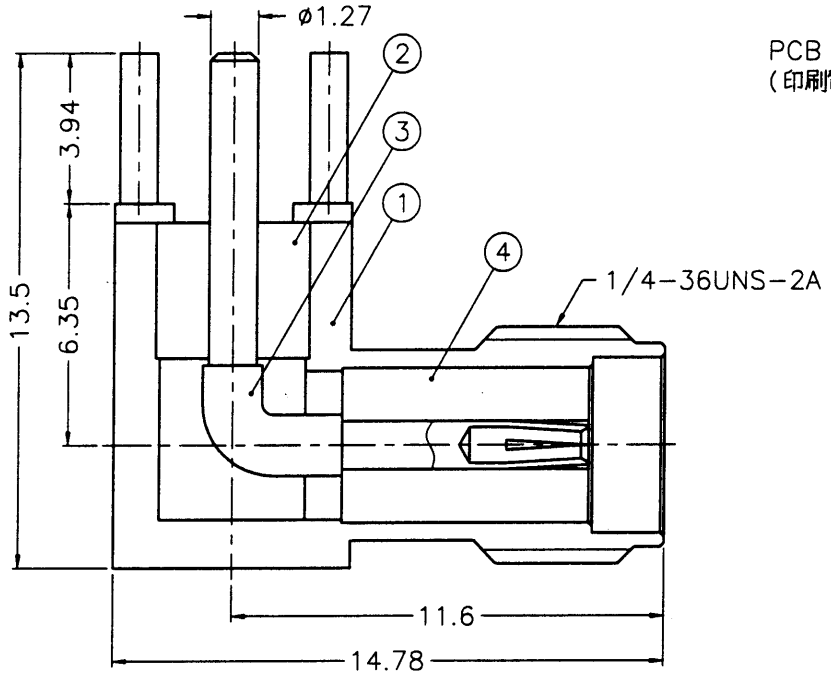


1 2 3 4 5 6 7 8

REVISIONS		
ISS	ZONE	DESCRIPTION\PER REQUEST\DATE
B	A-1	NO.4 WAS CHANGED\RD-DM89012701B\01-27-00'
C	A-1	NO.3 WAS CHANGED\RD-DM91011001K\01-10-02'
	E-7	PCB MOUNTING HOLE WAS CHANGED\N/A\09-20-02'



PCB MOUNTING HOLE
(印刷电路板架設孔)



NOTES: FINISH (PLATING THICKNESS IN MICRO-INCHES)
 1. GOLD PL. 3 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER PL. 300 MIN. STRIKE
 2. BERYLLIUM COPPER PER QQ-C-530
 3. GOLD PL. 50 MIN. THICK OVER NICKEL PL. 100 MIN. THICK OVER COPPER STRIKE
 4. TEFLON MIL-P-19468
 5. ZINC DIECAST

NO.	DESCRIPTION	MATERIAL	FINISH	Q'TY	DRAWING NO.
4	INSULATOR	NOTE 4	NATURAL	1	SMA6252D1-4
3	CONTACT PIN	NOTE 2	NOTE 3	1	SMA6252A2-4-B
2	INSULATOR	NOTE 4	NATURAL	1	SMA7790-5T-50
1	BODY	NOTE 5	NOTE 1	1	SMA6252D1-1

DIMENSIONS ARE IN MILLIMETERS				PART NO.		
UNLESS OTHERWISE SPECIFIED TOLERANCES 0.5-6 = ±0.2 6-30 = ±0.4 30-120 = ±0.6 120-315 = ±1 315-1000 = ±1.6 1000-2000 = ±2.4				APPROVED	DATE	
				<i>gajckey</i>		09-20-02'
				CHECKED	DATE	
				<i>Ken</i>		09-20-02'
DRAWN		DATE				
<i>Ken</i>		09-20-02'				
SCALE	5/1	ISSUE	C	FILE NO.	F:\DWG\SMA\6252D1\50\3GT50G	

Amphenol - Kai Jack	
TAINAN TAIWAN	
TITLE	SMA R/A P.C. MOUNT JACK
DRAWING NO.	KJ-SMA6252D1-3GT50G-50
ITEM NO.	116252AAL66GA5F

1 2 3 4 5 6 7 8

7/2D-DR 1/5576 8